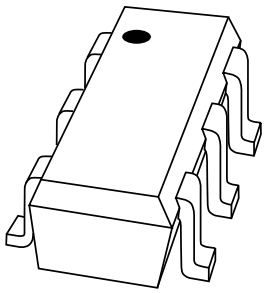
DATA SHEET



BGA2011

900 MHz high linear low noise amplifier

Product specification
Supersedes data of 2000 Sep 06

2000 Dec 04

900 MHz high linear low noise amplifier BGA2011

FEATURES

- Low current, low voltage
- High linearity
- High power gain
- Low noise
- Integrated temperature compensated biasing
- Control pin for adjustment bias current.

APPLICATIONS

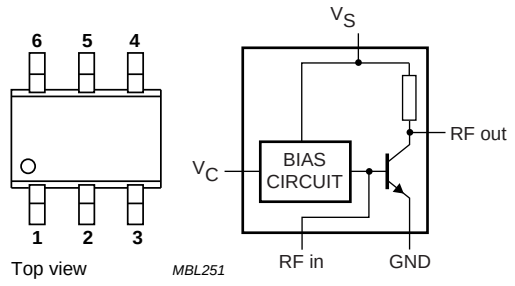
- RF front end
- Low noise amplifiers, e.g. CDMA, PHs, Dect, etc.

DESCRIPTION

Silicon Monolitic Microwave Integrated Circuit (MMIC) amplifier consisting of an NPN double polysilicon transistor with integrated biasing for low voltage applications in a 6-pin SOT363 plastic SMD package.

PINNING

PIN	DESCRIPTION
1	RF in
2	V_C
3	V_S
4	RF out
5, 6	GND



Marking code: A5-

Fig.1 Simplified outline (SOT363) and symbol.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V_S	DC supply voltage	RF input AC coupled	3	4.5	V
I_S	DC supply current		15	–	mA
I_C	DC control current	$V_C = V_S$	0.11	–	mA
$\|s_{21}\|^2$	insertion power gain	in application circuit, see Fig.2; f = 900 MHz	19	–	dB
NF	noise figure	I_S = 15 mA; f = 900 MHz	1.7	–	dB

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_S	DC supply voltage	RF input AC coupled	–	4.5	V
V_C	voltage on control pin		–	V_S	V
I_S	supply current	forced by DC voltage on RF input	–	30	mA
I_C	control current		–	0.25	mA
P_{tot}	total power dissipation	$T_s \leq 100$ °C	–	135	mW
T_{stg}	storage temperature		–65	+150	°C
T_j	operating junction temperature		–	150	°C

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j\text{-}s}$	thermal resistance from junction to solder point	P_{tot} = 135 mW; $T_s \leq 100$ °C	350	K/W

CHARACTERISTICS

RF input AC coupled; V_S = 3 V; I_S = 15 mA; f = 900 MHz; T_j = 25 °C; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I_S	supply current		10	15	20	mA
I_C	control current		–	0.11	–	mA
$R_{L\ IN}$	return losses input	typical application; see Fig.2	–	–11	–	dB
		high IP3 (see Fig.2; stripline = 0 mm)	–	–11	–	dB
		high IP3 (see Fig.2; stripline = 1.5 mm)	–	–17	–	dB
$R_{L\ OUT}$	return losses output	typical application; see Fig.2	–	–11	–	dB
		high IP3 (see Fig.2; stripline = 0 mm)	–	–12	–	dB
		high IP3 (see Fig.2; stripline = 1.5 mm)	–	–14	–	dB
$\lvert s_{21}\rvert^2$	insertion power gain	typical application; see Fig.2	–	15	–	dB
		high IP3 (see Fig.2; stripline = 0 mm)	–	19	–	dB
		high IP3 (see Fig.2; stripline = 1.5 mm)	–	16	–	dB
NF	noise figure	typical application; see Fig.2; I_S = 15 mA	–	1.5	–	dB
		high IP3 (see Fig.2; stripline = 0 mm)	–	1.6	–	dB
		high IP3 (see Fig.2; stripline = 1.5 mm)	–	1.7	–	dB
$IP3_{in}$	input intercept point	typical application; see Fig.2	–	–2	–	dBm
		high IP3 (see Fig.2; stripline = 0 mm)	–	4	–	dBm
		high IP3 (see Fig.2; stripline = 1.5 mm)	–	10	–	dBm

APPLICATION INFORMATION

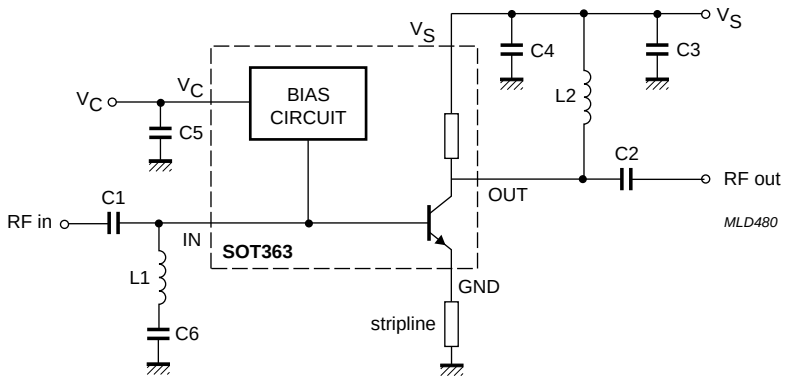


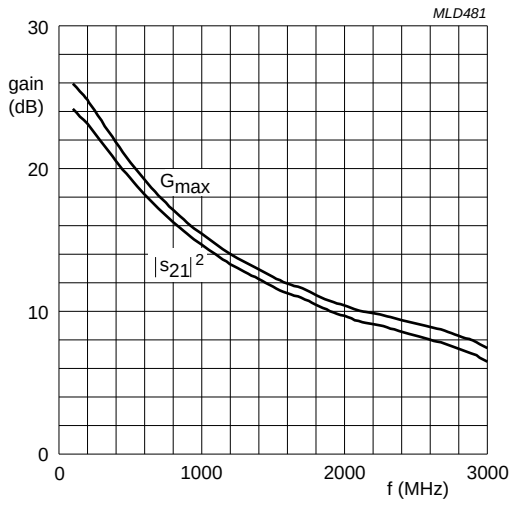
Fig.2 Application circuit.

List of components (see Fig.2)

COMPONENT	DESCRIPTION	TYPICAL APPLICATION	HIGH IP3 APPLICATION	DIMENSIONS
C1, C2	multilayer ceramic chip capacitor	100 pF	100 pF	0603
C3, C5	multilayer ceramic chip capacitor	22 nF	22 nF	0603
C4	multilayer ceramic chip capacitor	5.6 pF	5.6 pF	0603
C6	multilayer ceramic chip capacitor	–	2 x 100 nF	0805
L1	SMD inductor	–	10 nH	0603
L2	SMD inductor	–	8.2 nH	0603

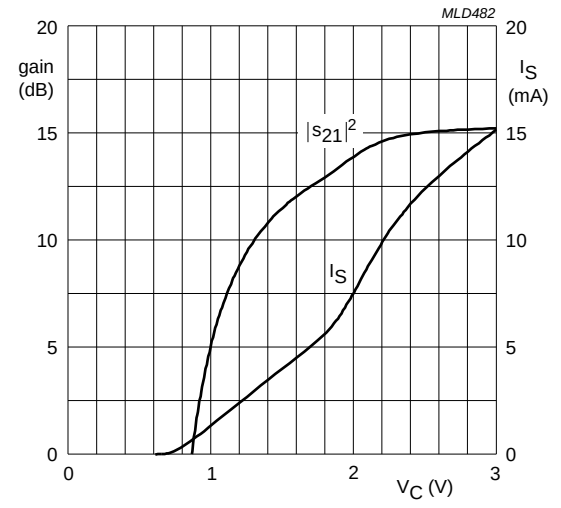
Note

1. The stripline (w = 0.7 mm) is on a gold plated double copper-clad printed-circuit board (ε_r = 6.15), board thickness = 0.64 mm, copper thickness = 35 μm, gold thickness = 5 μm.



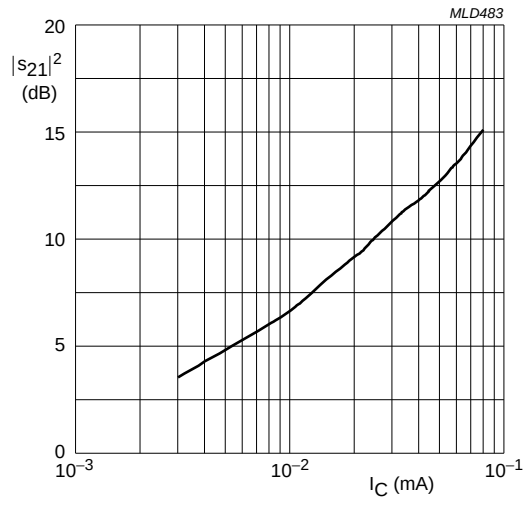
I_C = 15 mA; V_S = V_C = 3 V; P_D = −30 dBm; Z_o = 50 Ω.

Fig.3 Insertion gain ($|s_{21}|^2$) and G_{max} as functions of frequency; typical values.



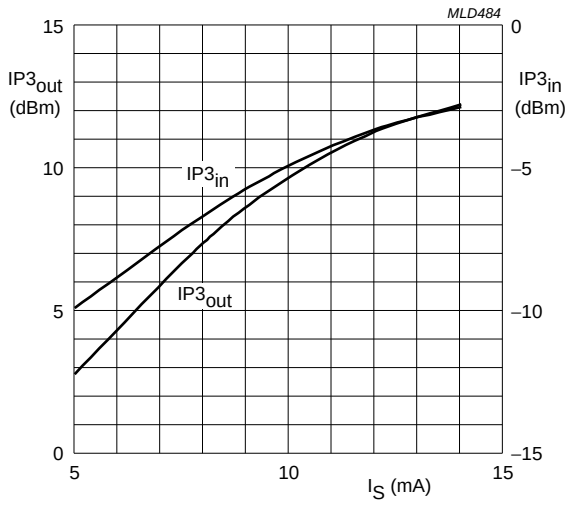
f = 900 MHz; V_S = 3 V; P_D = −30 dBm.

Fig.4 Insertion gain and supply current as functions of control voltage; typical values.



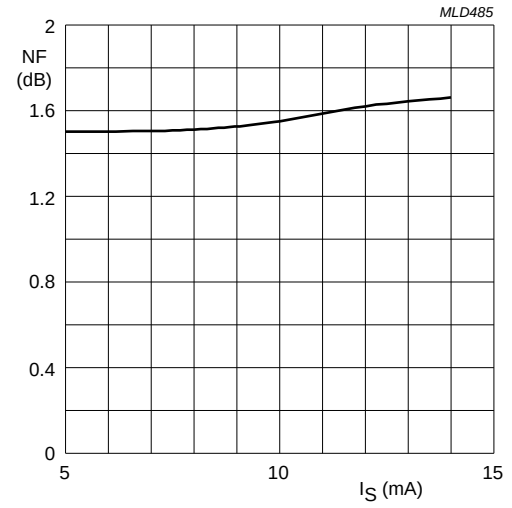
f = 900 MHz; V_S = 4 V; P_D = −30 dBm.

Fig.5 Insertion gain as a function of control current; typical values.



V_S = V_C = 3 V; P_D = −30 dBm (both tones); f = 900 MHz; Δf = 100 kHz.

Fig.6 Output and input 3rd order intercept point as a function of supply current; typical application; typical values.



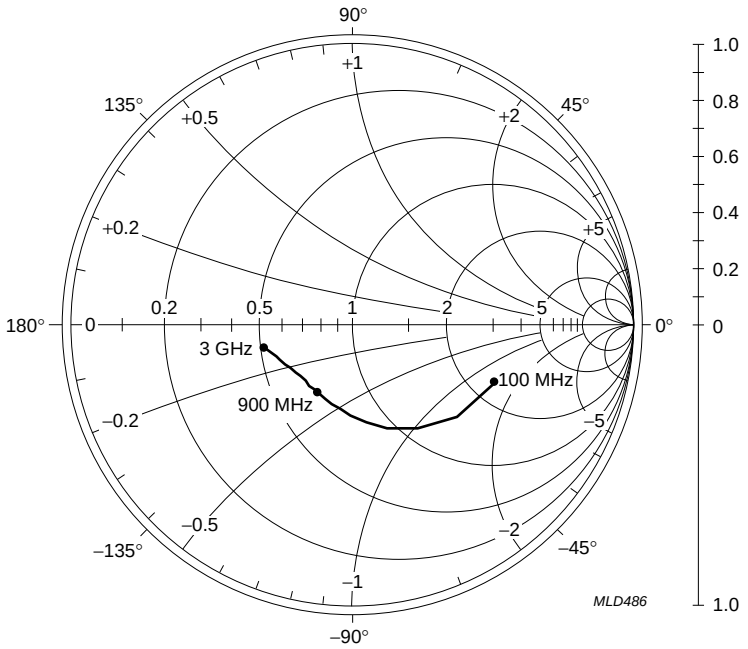
$V_S = V_C = 3$ V; f = 900 MHz.

Fig.7 Noise figure as a function of supply current; typical values.

Scattering parameters

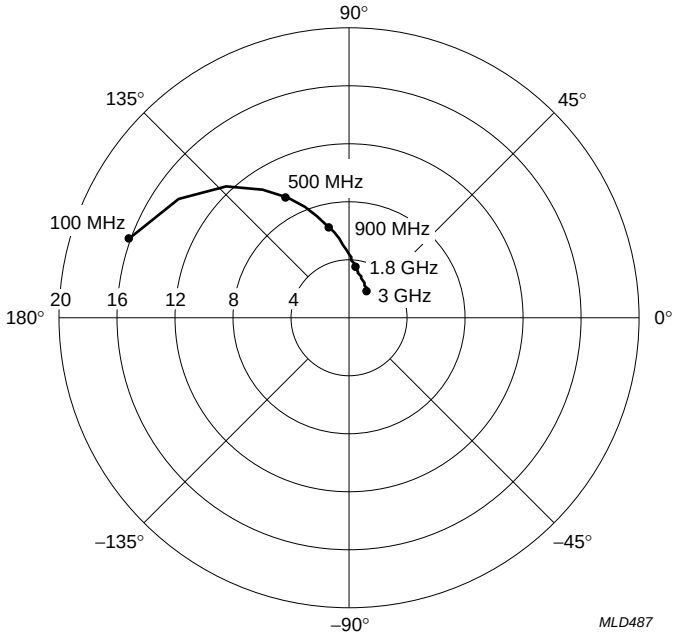
$V_S = V_C = 3$ V; $P_D = -30$ dBm; $Z_o = 50\ \Omega$; $T_{amb} = 25$ °C

f (MHz)	s_{11}		s_{21}		s_{12}		s_{22}	
	MAGNITUDE (ratio)	ANGLE (deg)	MAGNITUDE (ratio)	ANGLE (deg)	MAGNITUDE (ratio)	ANGLE (deg)	MAGNITUDE (ratio)	ANGLE (deg)
100	0.553	−22.45	16.198	160.5	0.006	76.72	0.115	−87.98
200	0.499	−42.12	14.354	145.4	0.012	67.53	0.184	−113.5
400	0.394	−71.44	10.688	124.6	0.018	59.55	0.256	−141.2
600	0.331	−90.58	8.156	112.2	0.021	58.29	0.283	−158.1
800	0.295	−104.0	6.512	103.9	0.024	60.91	0.293	−170.5
1000	0.276	−114.9	5.415	97.72	0.027	64.65	0.298	178.7
1200	0.267	−124.2	4.640	93.01	0.032	69.04	0.304	169.5
1400	0.262	−134.2	4.112	89.10	0.037	73.22	0.310	162.5
1600	0.270	−144.2	3.659	85.21	0.043	75.43	0.311	157.0
1800	0.287	−152.7	3.336	82.21	0.049	77.84	0.309	152.7
2000	0.309	−159.7	3.045	78.21	0.057	78.60	0.312	150.5
2200	0.339	−166.2	2.849	73.94	0.066	77.96	0.304	149.6
2400	0.360	−172.0	2.680	69.19	0.076	75.04	0.291	151.4
2600	0.390	−175.9	2.511	64.60	0.086	74.92	0.292	149.2
2800	0.398	178.0	2.332	59.20	0.094	69.95	0.278	148.4
3000	0.392	173.9	2.108	56.72	0.099	69.12	0.317	140.0



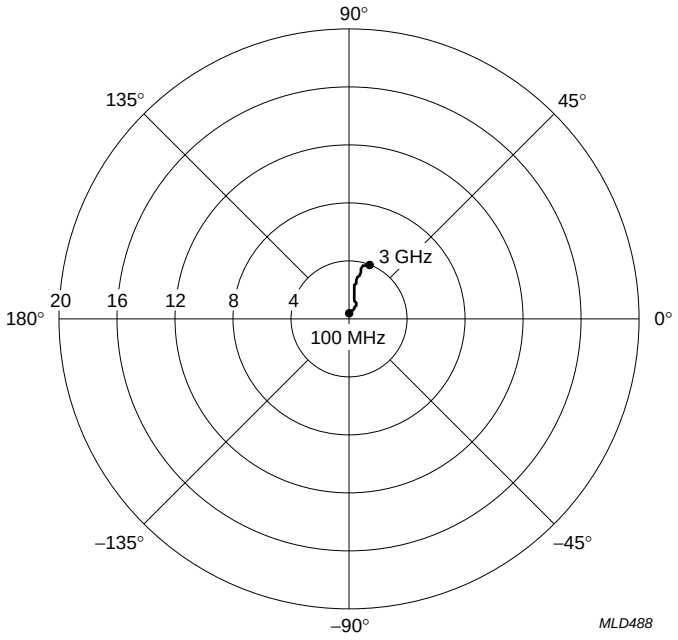
I_C = 15 mA; $V_S = V_C$ = 3 V; P_D = –30 dBm; Z_o = 50 Ω.

Fig.8 Common emitter input reflection coefficient (s_{11}); typical values.



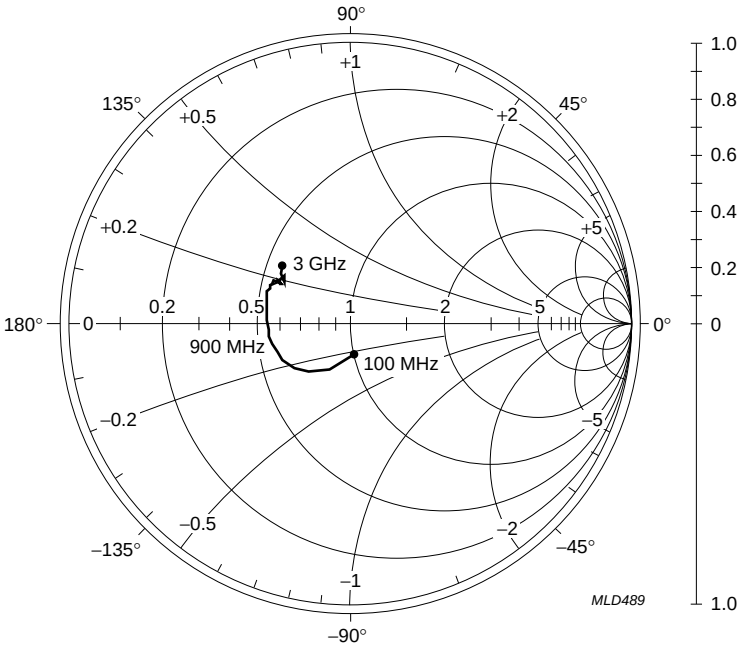
I_C = 15 mA; $V_S = V_C$ = 3 V; P_D = –30 dBm; Z_o = 50 Ω.

Fig.9 Common emitter forward transmission coefficient (s_{21}); typical values.



I_C = 15 mA; V_S = V_C = 3 V; P_D = −30 dBm; Z_o = 50 Ω.

Fig.10 Common emitter reverse transmission coefficient (s_{12}); typical values.

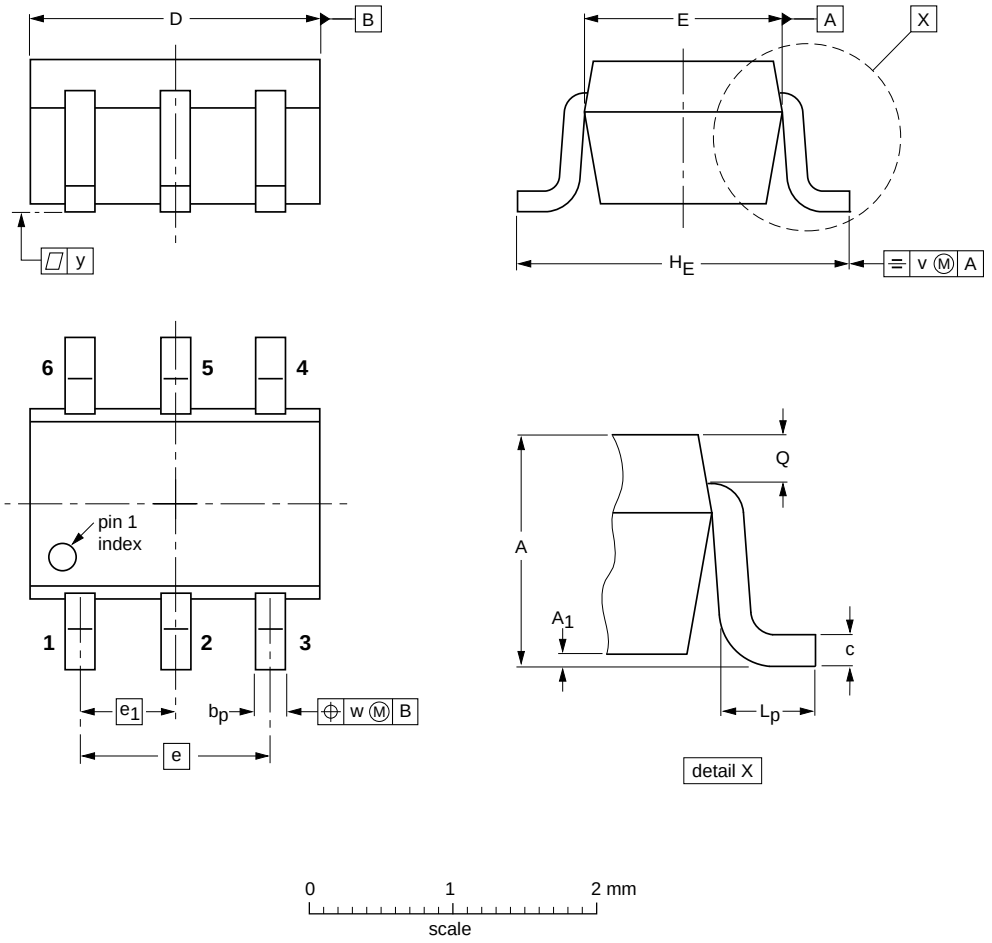


I_C = 15 mA; V_S = V_C = 3 V; P_D = −30 dBm; Z_o = 50 Ω.

Fig.11 Common emitter output reflection coefficient (s_{22}); typical values.

PACKAGE OUTLINE

Plastic surface-mounted package; 6 leads **SOT363**



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1 max	b_p	c	D	E	e	e_1	H_E	L_p	Q	v	w	y
mm	1.1 0.8	0.1	0.30 0.20	0.25 0.10	2.2 1.8	1.35 1.15	1.3	0.65	2.2 2.0	0.45 0.15	0.25 0.15	0.2	0.2	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT363			SC-88			~~04-11-08~~ 06-03-16

DATA SHEET STATUS

DOCUMENT STATUS[1]	PRODUCT STATUS[2]	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

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